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(54) Title: DUAL LOADING RETAINING RING

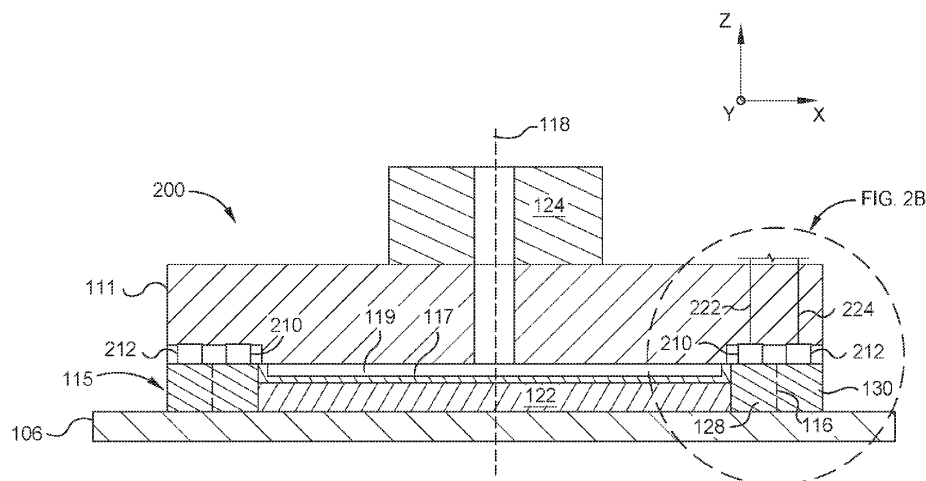


FIG. 2A

(57) Abstract: A substrate carrier configured to be attached to a polishing system for polishing a substrate is described herein. The substrate carrier includes a housing including a plurality of load couplings and a retaining ring coupled to the housing. The retaining ring can include an annular body having a central axis, an inner edge facing the central axis of the annular body, the inner edge having a diameter configured to surround a substrate, and an outer edge opposite the inner edge, wherein the plurality of load couplings contact the retaining ring at different radial distances measured from the central axis, and wherein the plurality of load couplings are configured to apply a radially differential force to the retaining ring.

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